

ABSTRACT

An assembly having a surface mounted electronic
5 device mounted onto a printed circuit board and a
thermoplastic adhesive applied to the surface mounted
electronic device facing the printed circuit board and
providing for a gap between the thermoplastic adhesive
and the printed circuit board. The assembly is heated at
10 solder reflow temperatures to at least soften the
thermoplastic adhesive sufficiently to flow across the
gap and provide a thermoplastic adhesive joint between
the surface mounted electronic device and the printed
circuit board.